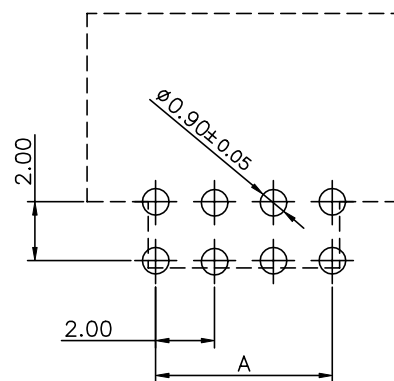
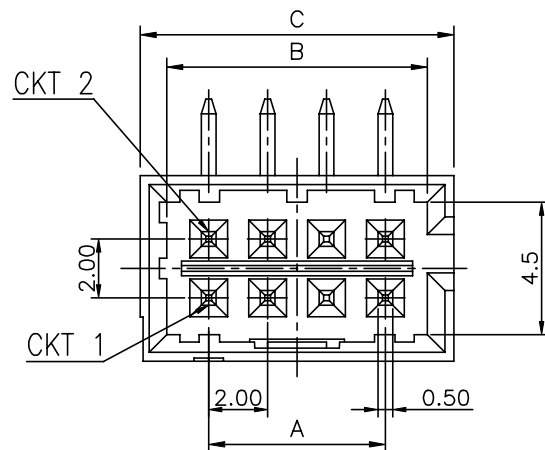
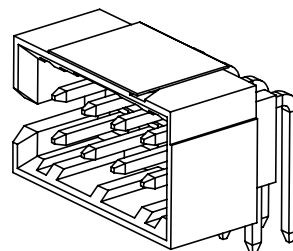
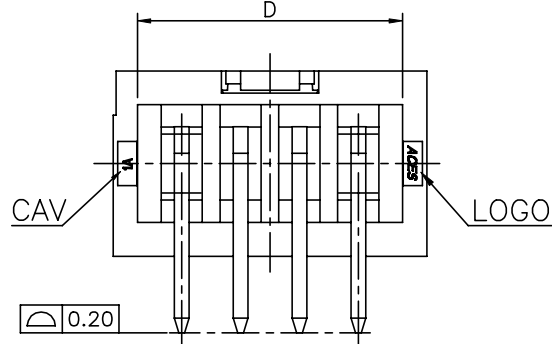
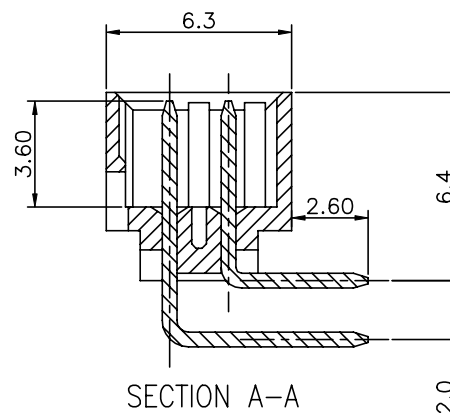
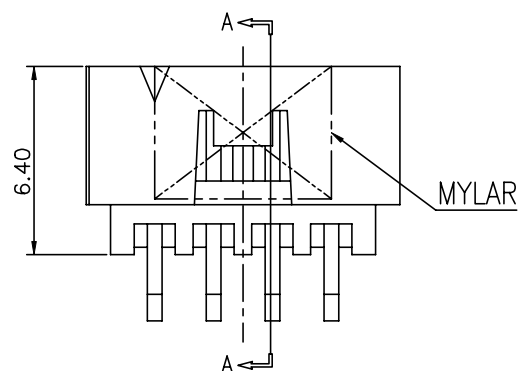




RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05



NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK
- 1.2 TERMINAL: COPPER ALLOY

2. FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.

2.1 CONTACT AREA:

C: 15u" GOLD

2.2 SOLDER AREA:

MATTE TIN

3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-51352-XXXX-XXX

5. PART NUMBER

51352-XXX X X-XXX

CKTS

PACKING

- 1.TUBE
- 5.TUBE WITH MYLAR

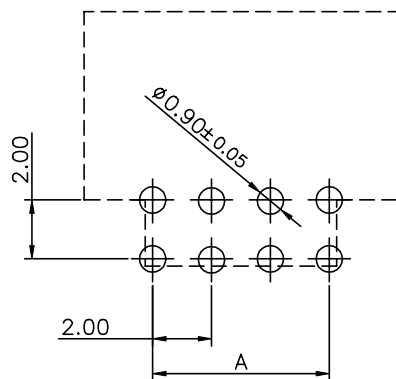
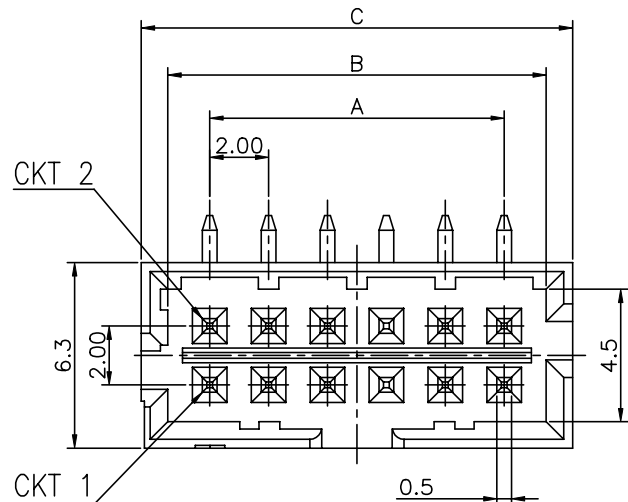
C: GOLD 15u" ON CONTACT,
MATTE TIN ON SOLDER

XXX	CENTER LOCK	COLOR
001	Y	BLACK

PLATING

CKT	DIM A	DIM B	DIM C	DIM D
8	6.00	8.85	10.65	9.00

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X. ± 0.5 X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2^\circ$	DRAWN BY Huang,ShunSen	DATE 23/08/01		
	CHECKED BY Lu, jing quan	DATE 23/08/01		
	APPROVED BY hsieh,fu yu	DATE 23/08/01	TITLE 2.0mm WTB WAFER CONN T/H D/R R/A TYPE.	
	UNITS mm		SIZE A4	RFQ NO. NA
SCALE 1:1	SHEET NO. 1 OF 3	REV D	DWG NO. 51352-XXXX-XXX	



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

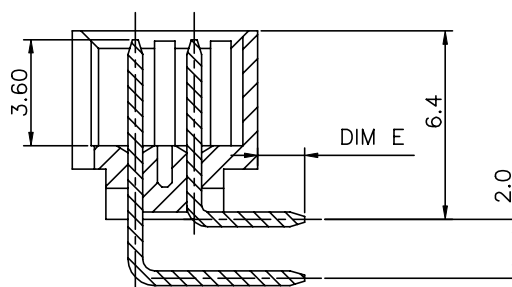
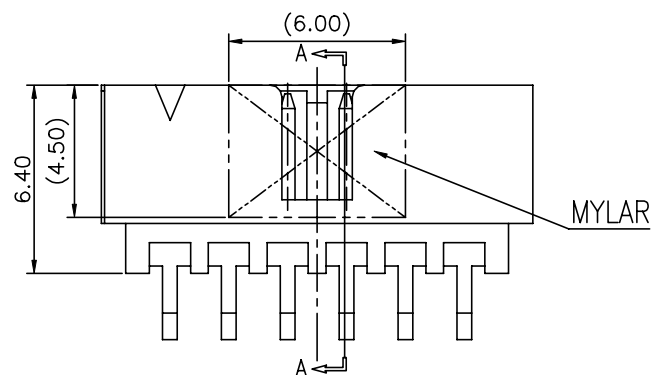
NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK
 - TERMINAL: COPPER ALLOY
- FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.
 - CONTACT AREA: C: 15u" GOLD
 - SOLDER AREA: MATTE TIN
- REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- SPEC. PLS. REFER TO PS-51352-XXXXX-XXX
- PART NUMBER

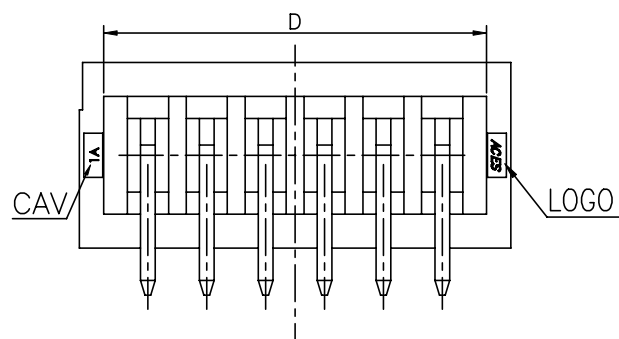
51352-XXX X X-XXX
CKT-
PACKING
4:T&R WITH MYLAR
5.TUBE WITH MYLAR

XXX	CENTER LOCK	COLOR	PACKING	DIM E
002	N	BLACK	51352-XXXXX-00-TRP	1.6
003	N	BLACK	51352-XXXXX-05-TRP	2.16

PLATING
C:GOLD 15u" ON CONTACT
MATTE TIN ON SOLDER

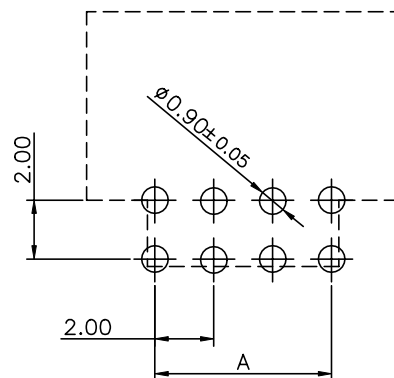
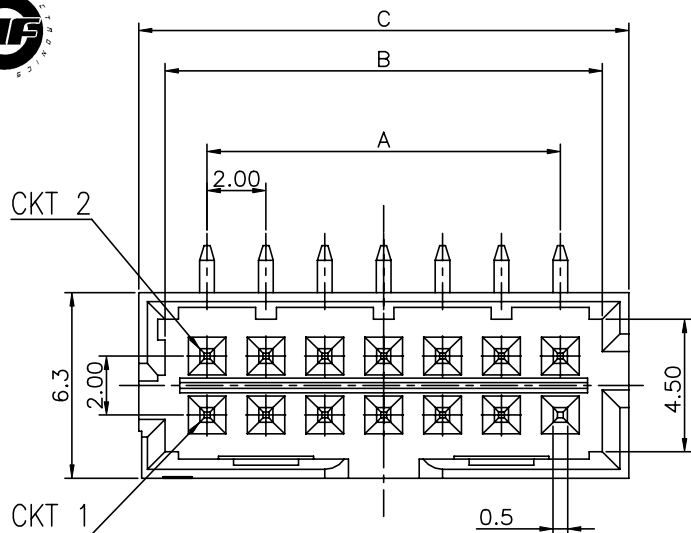


SECTION A-A



CKT	DIM A	DIM B	DIM C	DIM D
8	6.00	8.85	10.65	9.00
12	10.00	12.85	14.65	13.00

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X. ± 0.5 X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2^\circ$	DRAWN BY Huang,ShunSen	DATE 23/08/01	 2.0mm WTB WAFER CONN T/H D/R R/A TYPE.	
	CHECKED BY Lu, jing quan	DATE 23/08/01		
	APPROVED BY hsieh,tu yu	DATE 23/08/01		
	UNITS mm			
SCALE 1:1	SHEET NO. 2 OF 3	SIZE A4	REV D	RFQ NO. NA
			DWG NO. 51352-XXXXX-XXX	



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR BLACK
 - TERMINAL: COPPER ALLOY
- FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.
 - CONTACT AREA:
 - G/F
 - C: GOLD 15u"
 - SOLDER AREA: MATTE TIN
- REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- SPEC. PLS. REFER TO PS-51352-XXXXX-XXX
- PART NUMBER

51352-XXX X X-XXX

CKT

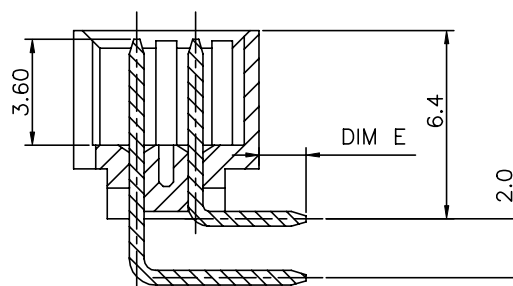
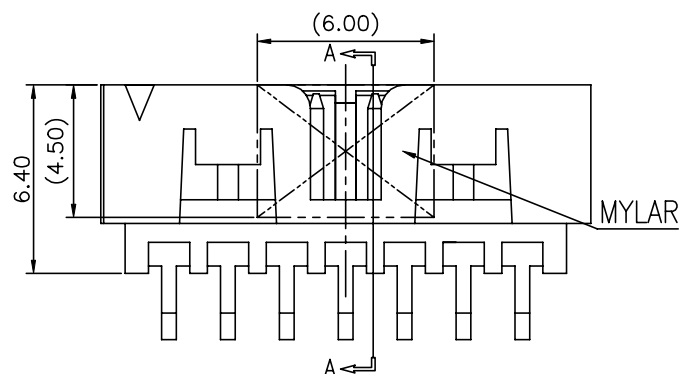
PACKING

4:T&R WITH MYLAR
5.TUBE WITH MYLAR

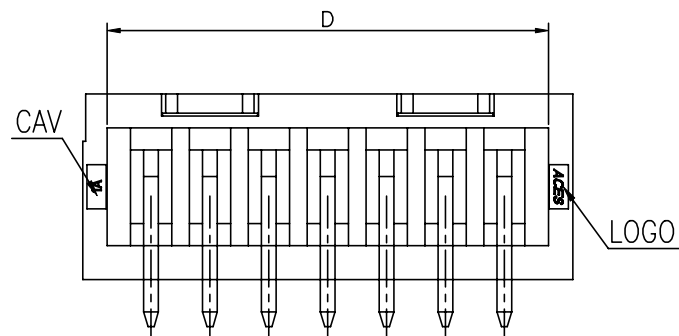
PLATING

C:GOLD 15u" ON CONTACT
MATTE TIN ON SOLDER
1: G/F

XXX	CENTER LOCK	COLOR	PACKING	DIM E
001	N	BLACK	51352-XXXXX-07-TRP	2.6
002	N	BLACK	51352-XXXXX-00-TRP	1.6
003	N	BLACK	51352-XXXXX-05-TRP	2.16



SECTION A-A



CKT	DIM A	DIM B	DIM C	DIM D
14	12.00	14.85	16.65	15.00

QUALITY SYMBOLS MAJOR  CRITICAL 	DRAWN BY		DATE		
	Huang,ShunSen		23/08/01		
	CHECKED BY		DATE		
	Lu, jing quan		23/08/01		
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ± 0.5 X ± 0.25 .XX ± 0.15 XXX ± 0.1 ANGLES $\pm 2^{\circ}$	APPROVED BY		DATE		TITLE 2.0mm WTB WAFER CONN T/H D/R R/A TYPE.
	hsieh,fu yu		23/08/01		
	UNITS		SIZE	RFQ NO.	
	mm		A4	NA	
	SCALE 1 : 1	SHEET NO. 3 OF 3	REV D	DWG NO. 51352-XXXXX-XXX	